ECAL-P mechanical frame

status report on the design

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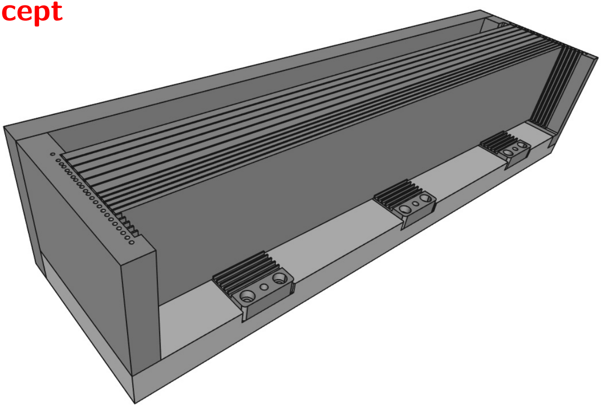
ECAL-P main mechanical frame

Design concept

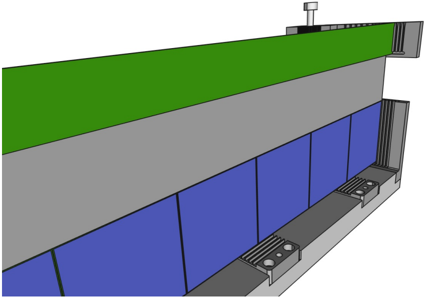


Concept of the main frame (for tungsten planes only) ready.
Assuming $10 \times 1\,X_0 \; + \; 6 \times 2\,X_0$ absorber layers (15 sensor layers).

Proposed approach assumes modular structure of the design.

ECAL-P PCB frame

Next steps



First concept of the frame holding PCBs

Assuming sensors in carbon fiber envelopes are attached to PCBs

⇒ no additional support needed.

Still to be considered:

- mechanical arm for lowering PCBs with sensor planes in the structure
- frame support for proper positioning on the table (meeting tomorrow)
- additional structures for holding cables, covers etc.